



• General Description

It combines trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. It is suitable for automotive application.

• Features

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

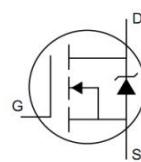
- BLDC Motor driver
- DC-DC
- Load switch

• Ordering Information:

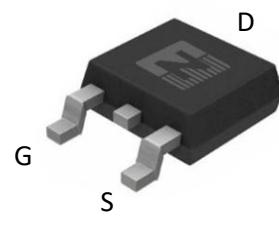
Part NO.	ZMA098N06D
Marking	ZM098N06
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

• Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		60	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_c=25^\circ\text{C}$	50	A
	I_D	$T_c=75^\circ\text{C}$	44	A
	I_D	$T_c=100^\circ\text{C}$	38	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$	200	A
Total Power Dissipation	P_D	$T_c=25^\circ\text{C}$	83	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	2.4	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	47	mJ
		$L=0.5\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	99	mJ
ESD Level (HBM)			CLASS 2	



$V_{DS}=60\text{V}$
 $R_{DS(ON)}=10\text{m}\Omega$
 $I_D=50\text{A}$



TO-252



HF



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}		-	1.8	°C/W
Thermal resistance, junction-ambient ^②	R _{thJA}		-	62	°C/W
Soldering temperature (total time<10s)	T _{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	60			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	1.4	1.7	2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{GS} =0V, V _{DS} = 60V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D = 24A		10	13	mΩ
		V _{GS} =4.5V, I _D = 12A		12	15	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _{SD} = 10A		14		s
Diode Forward Voltage	V _{FSD}	V _{GS} =0V, I _{SD} = 24A			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz, V _{DS} =25V	-	2750	-	pF
Output capacitance	C _{oss}		-	185	-	
Reverse transfer capacitance	C _{rss}		-	135	-	
Gate Resistance	R _g	f = 1MHz	-	1.9		Ω
Total gate charge	Q _g	V _{DD} = 15V, I _D = 20A, V _{GS} = 10V	-	30	-	nC
	Q _g (4.5v)		-	17	-	
Gate - Source charge	Q _{gs}	V _{GS} = 10V, V _{DS} = 15V, R _G =3.3Ω, I _D =20A	-	8.4	-	nC
Gate - Drain charge	Q _{gd}		-	5.8	-	
Turn-ON Delay time	t _{D(on)}	V _{GS} =10V, V _{DS} =15V, R _G =3.3Ω, I _D =20A	-	17	-	ns
Turn-ON Rise time	t _r		-	40	-	ns
Turn-Off Delay time	t _{D(off)}		-	22	-	ns
Turn-Off Fall time	t _f		-	12	-	ns
Reverse Recovery Time	t _{RR}	V _{DD} =20V, dI _S /dt = 100A/s, I _S =20A	-	50	-	ns
Reverse Recovery Charge	Q _{RR}		-	46	-	nC



Fig.1 Gate-Charge Characteristics

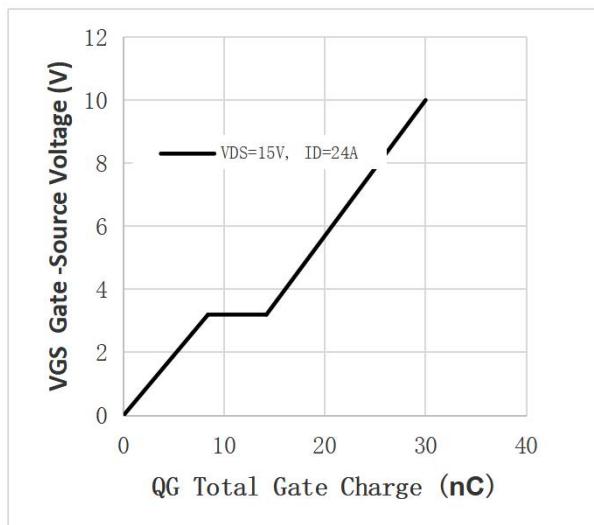


Fig.2 Capacitance Characteristics

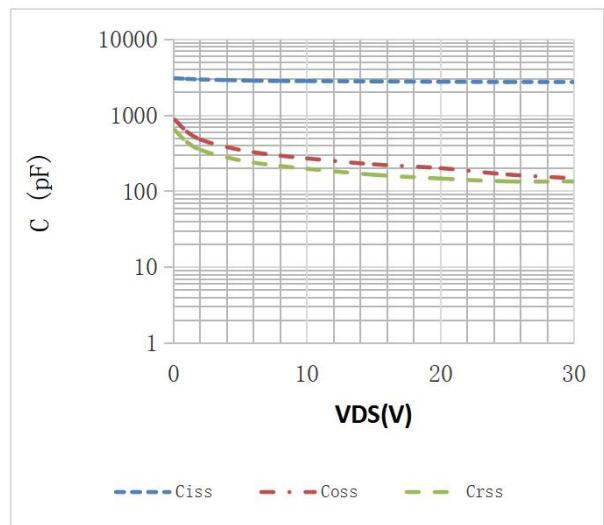


Fig.3 Power Dissipation

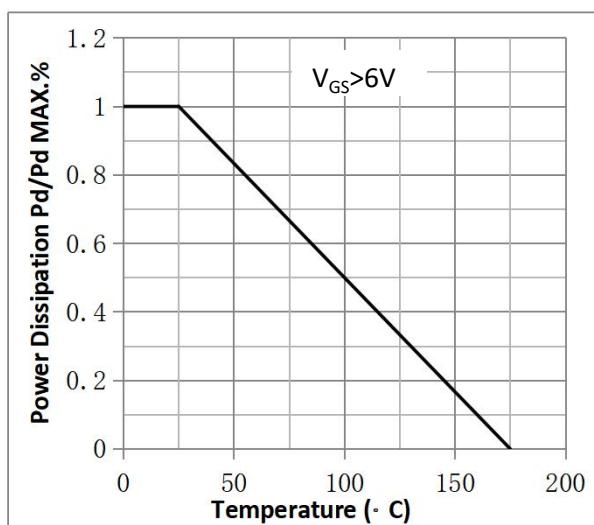


Fig.4 Typical output Characteristics

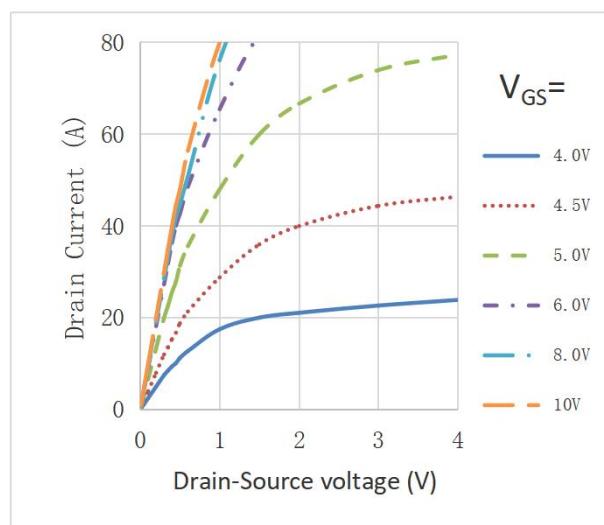


Fig.5 Threshold Voltage V.S Junction Temperature

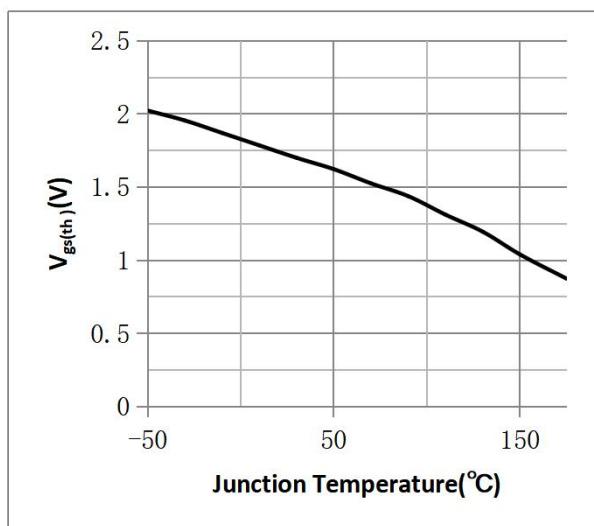


Fig.6 Resistance V.S Drain Current

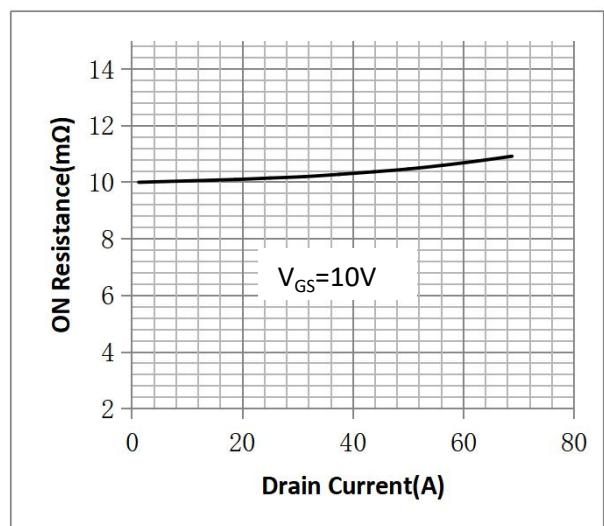


Fig.7 On-Resistance VS Gate Source Voltage

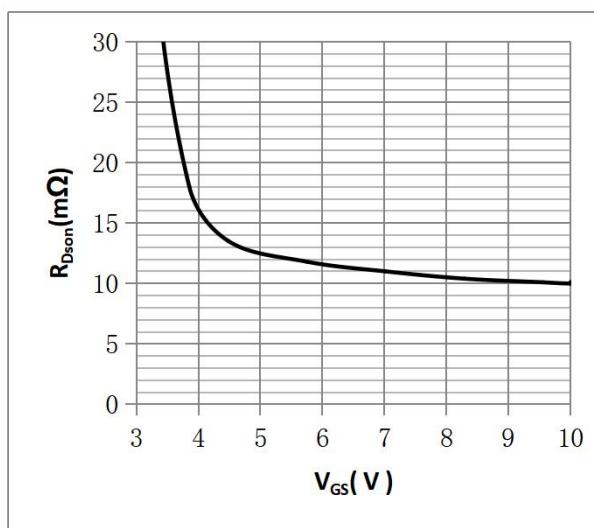


Figure 9. Diode Forward Voltage vs. Current

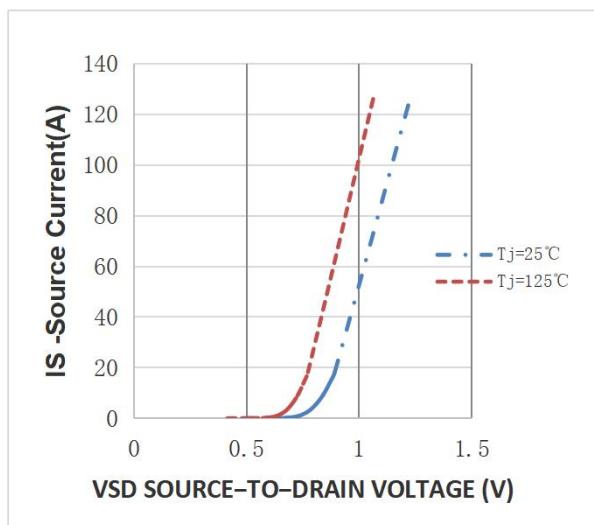


Fig.11 Safe Operating Area

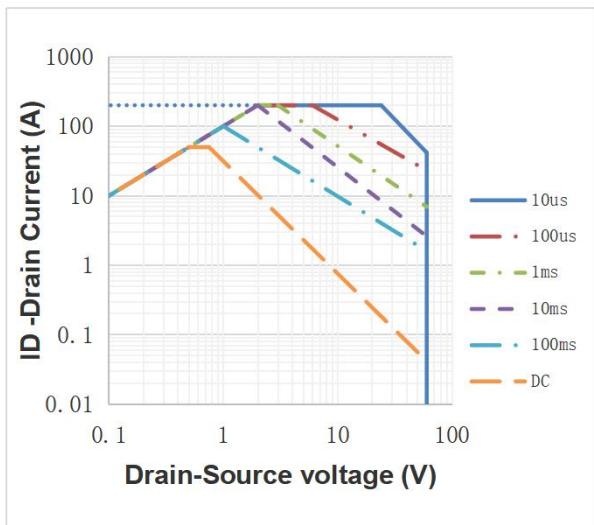


Fig.8 On-Resistance V.S Junction Temperature

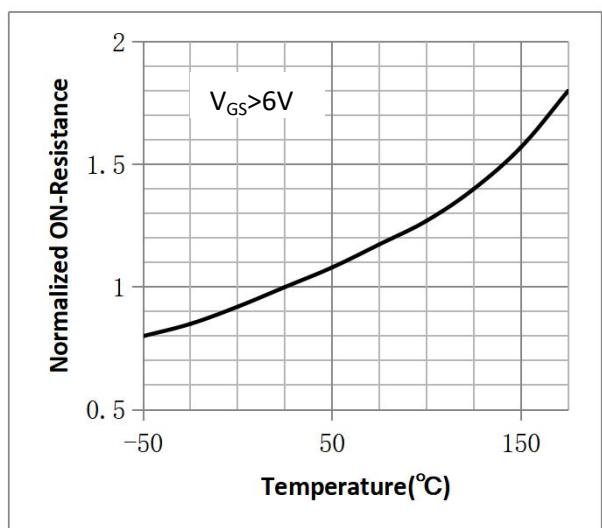
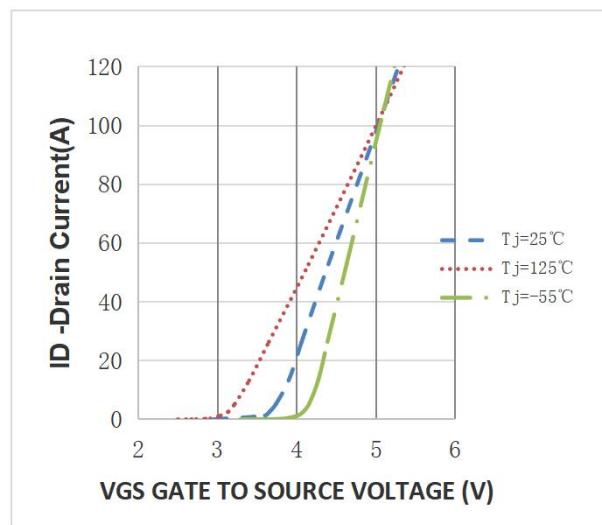
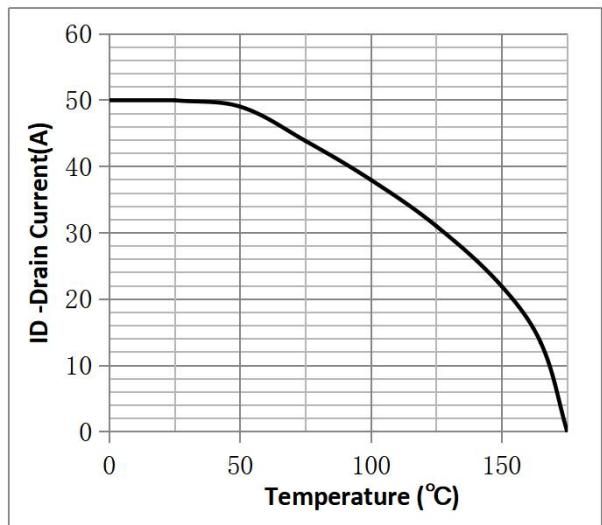


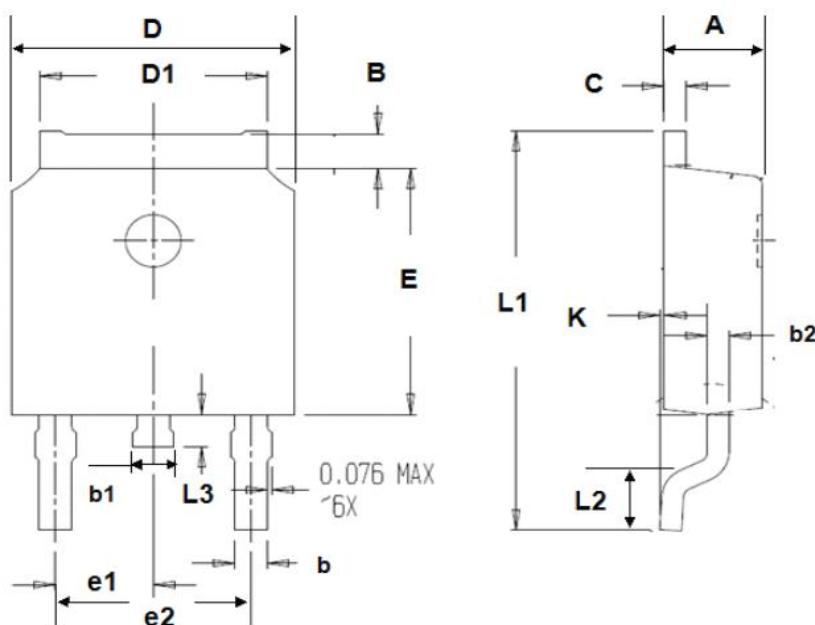
Figure 10. Transfer Characteristics

Fig.12 ID vs. Case Temperature^③



•TO-252 Package Outline

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	B	0.85	1.25
b	0.50	0.90	b1	0.50	0.90
b2	0.45	0.70	C	0.45	0.70
D	6.30	6.75	D1	5.10	5.50
E	5.30	6.30	e1	2.24	2.35
L1	9.20	10.60	e2	4.43	4.75
L2	0.90	1.75	L3	0.60	1.10
K	0.00	0.23			



**Note:**

- ① Pulse : VGS=+20V/-20V, Duty cycle=50%, Tj=175°C, t=1000 hours; For DC , the following test conditions can be passed: VGS=+20V/-10V, Tj=175°C, t=1000 hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. VGS=10V.

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Revision History

Version	Date	Change
A	2020.3.10	NEW
B	2021.11.23	1.Add dynamic characteristics
C	2022.10.12	1.Fig1~12 modify 2.Modify ID curve 4.Add Dynamic characteristics